



# SYSTEMATIC CHARACTERIZATION OF THE SiC/SiO<sub>2</sub> TRANSITION LAYER IN NO-ANNEALED MOSFETS

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# Outline

- Introduction, Motivation, Background, Goals
- Experimental Methods
  - EELS, Spectrum Imaging,  $w_{TL}$  determination
- Transition layer width results
  - Composition ratios
  - Interdiffusion
  - HAADF-STEM
  - Chemical shift
- Correlation with electronic measurements
- Conclusions, Remaining questions, etc.

# Motivation and Background

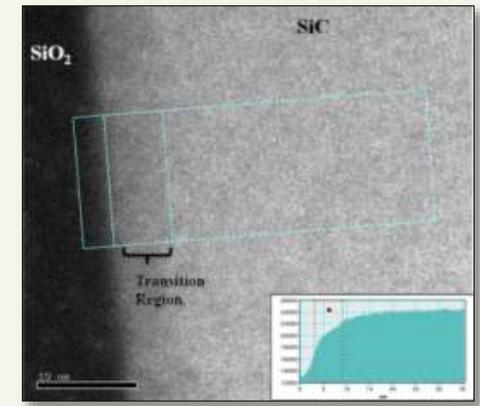
- SiC: Very promising for high temperature, high power, and high frequency devices
  - 4H polytype (bulk):<sup>1</sup>  $E_g = 3.23 \text{ eV}$ ,  $\mu_e \approx 850 \frac{\text{cm}^2}{\text{V}\cdot\text{s}}$ ,  $\epsilon = 10$ ,  $\kappa = 3.7 \frac{\text{W}}{\text{cm}\cdot^\circ\text{C}}$
  - MOSFET devices limited by poor channel carrier mobility and reliability
  - Electrically active defects at the SiC/SiO<sub>2</sub> interface inhibit devices during channel inversion
- Possible nature of these defects?

Excess carbon at the interface (maybe?)	K. Chang, <i>et al.</i> J. Electron. Mater. <b>32</b> , 464 (2003). X. Shen, <i>et al.</i> J. Appl. Phys. <b>108</b> , 123705 (2010). Hatakeyama, <i>et al.</i> Mater. Sci. Forum <b>679</b> , 330 (2010).
3-fold Si and C coordination and C <sub>i</sub>	M. DiVentra, <i>et al.</i> Phys. Rev. Lett. <b>83</b> , 1624 (1999). S. Pantelides, <i>et al.</i> Mater. Sci. Forum <b>527</b> , 935 (2006).
V <sub>Si</sub> and V <sub>O</sub> at interface	C. Cochrane, <i>et al.</i> Appl. Phys. Lett. <b>100</b> , 23509 (2012). J. Rozen, <i>et al.</i> J. Appl. Phys. <b>105</b> , 124506 (2009).

<sup>1</sup>Semiconductor database: <http://www.ioffe.ru/SVA/NSM/Semicond/SiC/index.html>

# Previous Work

- Transition region around SiC/SiO<sub>2</sub> interface
  - EELS evidence of enhanced C concentration in SiC at interface
    - T. Zheleva, *et al.* Appl. Phys. Lett. **93**, 022108 (2008).
  - Transition layer width ( $w_{TL}$ ) lowered by NO post-anneal; measured with HAADF-STEM intensity profiles
    - Inverse linear correlation between  $w_{TL}$  and mobility
    - T. Biggerstaff, *et al.* Appl. Phys. Lett. **95**, 032108 (2009). →
- Our previous results (2010 - )
  - Not annealed, 240 min NO anneal, 20 hr N<sub>2</sub> plasma anneal, 4 and 6 hr O<sub>2</sub> plasma oxidation
  - Annealing in all cases yielded sharper interfaces than non-annealed
    - N<sub>2</sub> plasma most effective, but no systematic results

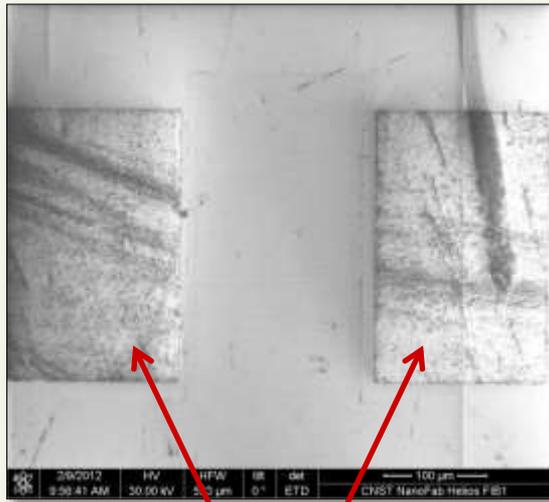


# Goals

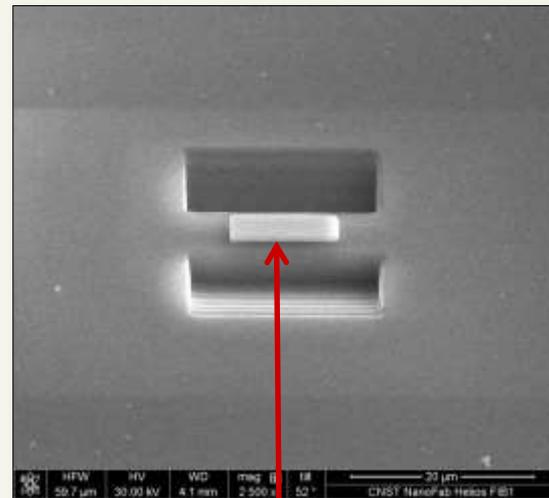
- Physically and chemically characterize transition layer as a function of NO post-annealing time
  - Systematic set of SiC MOSFETS that received 0, 15, 30, 60, 120, and 240 minute post-oxidation anneals at 1175°C
  - Using HRTEM, HAADF-STEM, and EELS
  - Correlate with measured device properties
  - Investigate conflicting claims of excess C at interface
- Develop reliable, objective, and reproducible methods by which to determine  $w_{TL}$ 
  - For comparison to previous works and future sample sets

# TEM Specimen Preparation

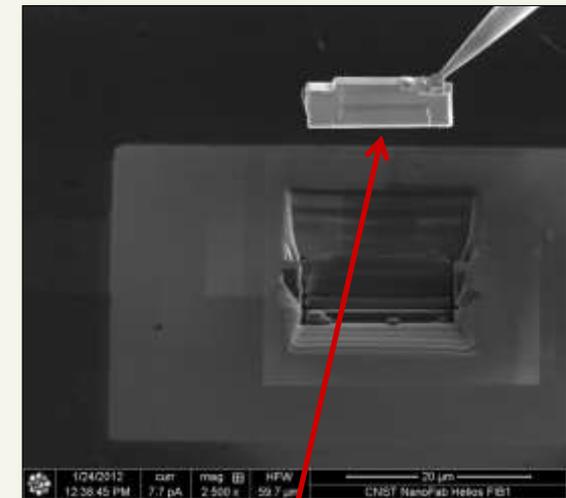
- Cross-sectional TEM specimen prepared with FIB
  - Mo gate metallization removed from devices with  $\text{H}_2\text{O}_2$  etch
  - Two protective Pt layers ( $e^-$  beam and ion beam deposited) prevent  $\text{Ga}^+$  ion implantation and oxide layer damage
  - Previous work used C protective layer, complicating analysis



S/D contacts



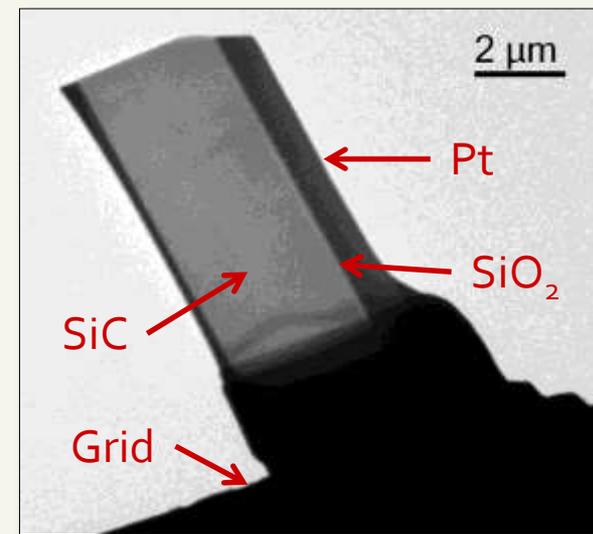
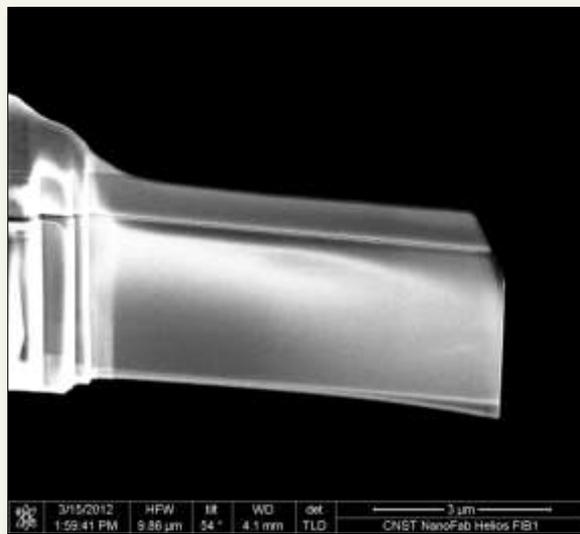
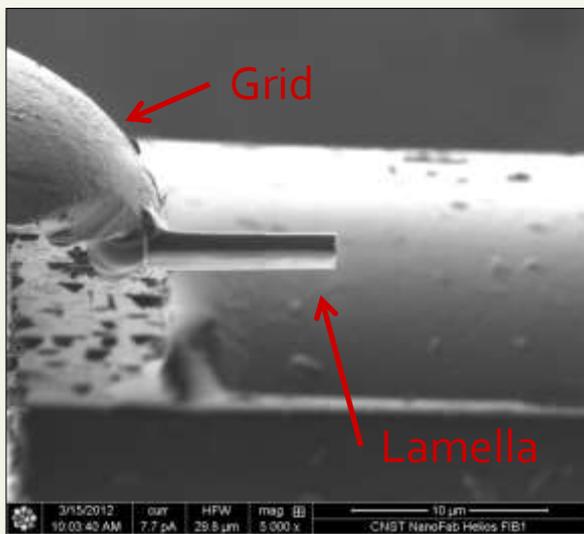
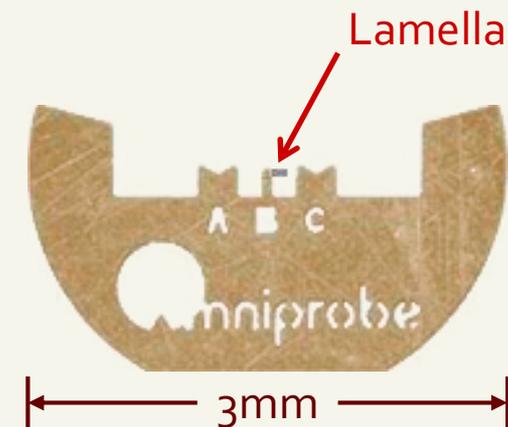
Protective Pt



Lamella removed with tungsten probe

# TEM Specimen Preparation

- Typical specimen dimensions
  - $6\mu\text{m} \times 3\mu\text{m} \times \approx 80\text{nm}$
  - Flat "flag" specimen attached to grid with Pt

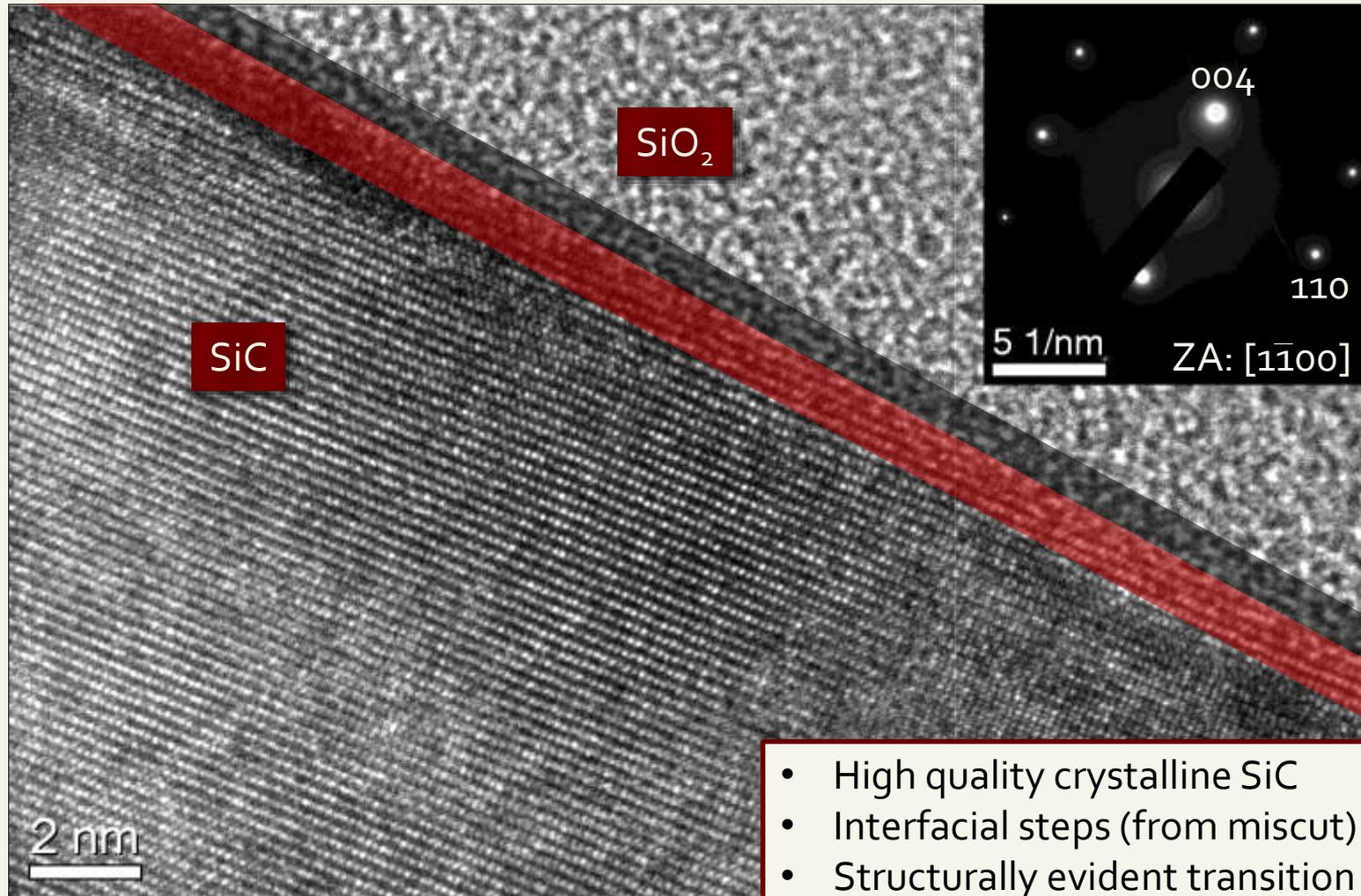


FIB image before thinning

SEM image after thinning

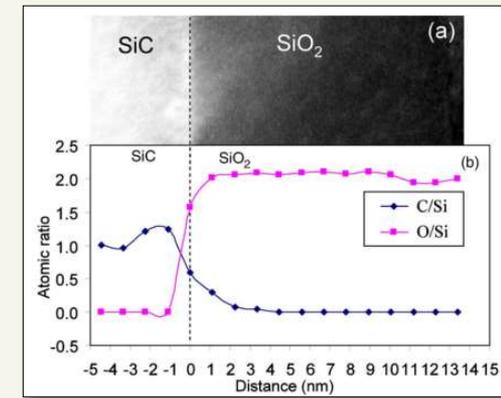
Low-mag TEM image

# HRTEM of Transition Layer



# Transition Layer Thickness Measures

- EELS composition ratios ( $C/Si$  and  $O/Si$ ) →
  - Zheleva, *et al.* Appl. Phys. Lett. **93**, 022108 (2008).
  - Eliminates many sources of systematic error<sup>1</sup>
- Relative “interdiffusion” of C and O (EELS)
  - Gives idea of transition layer on each side of interface
  - C into  $SiO_2$  and O into SiC
- HAADF-STEM image intensity profiles
  - HAADF reveals Z-contrast from variations in atomic composition
- Chemical shift of Si- $L_{2,3}$  EELS edge
  - Well-documented shift in edge onset energy (SiC: 100 eV;  $SiO_2$ : 104 eV)
    - G. Auchterlonie, *et al.* Ultramicroscopy, **31**, 217 (1989).
  - Reveals information about local Si bonding

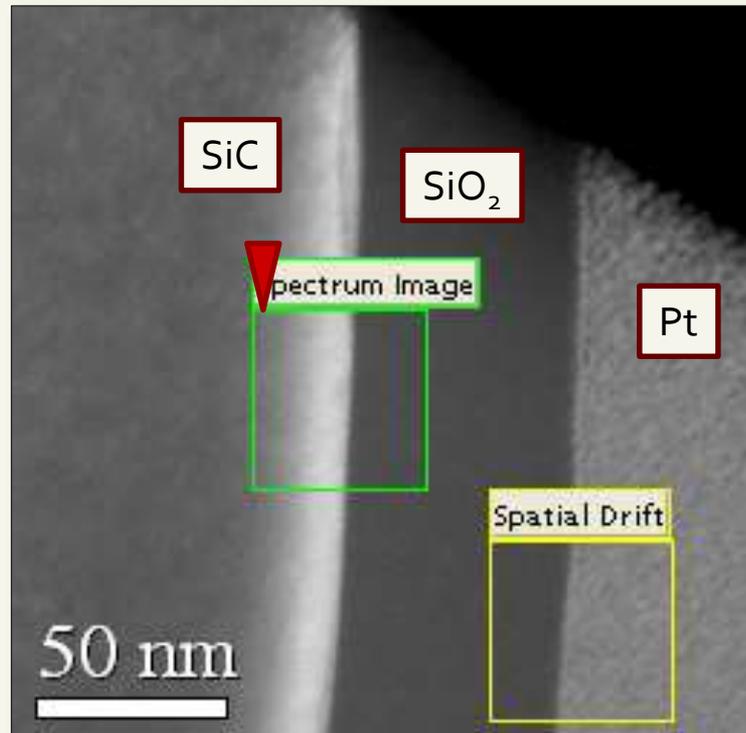


<sup>1</sup> R. Brydson and R.M.S. (UK), *Electron Energy Loss Spectroscopy*, Microscopy Handbooks (Bios, 2001).

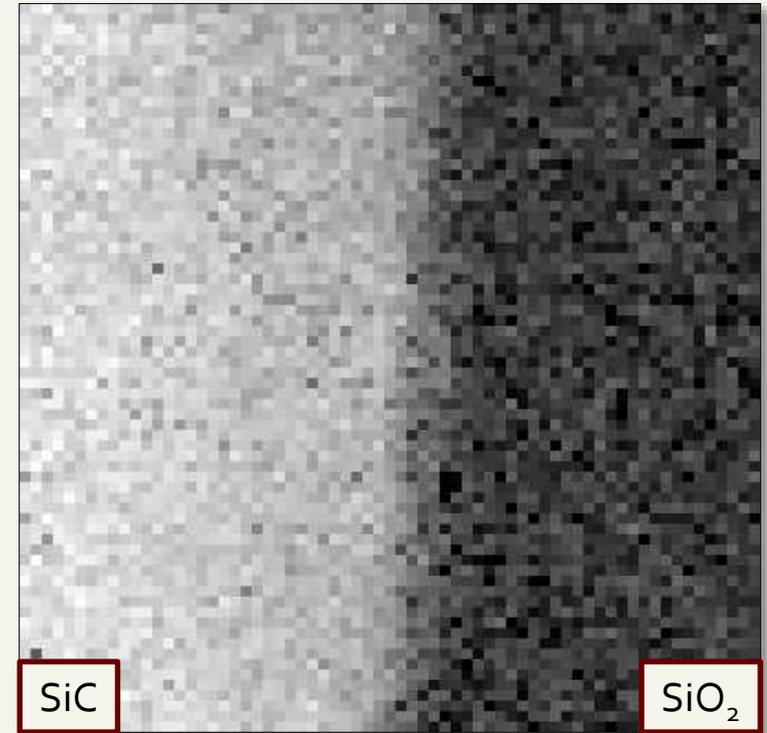
# EELS Experimental Methods

- Gatan Tridiem post-column imaging filter
  - Simultaneous HAADF-STEM imaging and EELS collection
- Spectrum imaging
  - Raster beam across sample, collecting a full EELS spectrum at each pixel
  - Spectrum image (SI) represents a map of spectra
  - Allows for short collection time, limited beam damage
  - Sum parallel to interface to improve  $S/N$  ratio
- Collection parameters:
  - Linear or areal SI across interface
  - Dwell time  $< 0.01$  s
  - Spot size ( $\sim$  spatial resolution) = 0.5 nm
  - Energy dispersion = 0.3 eV/channel

# Spectrum Imaging

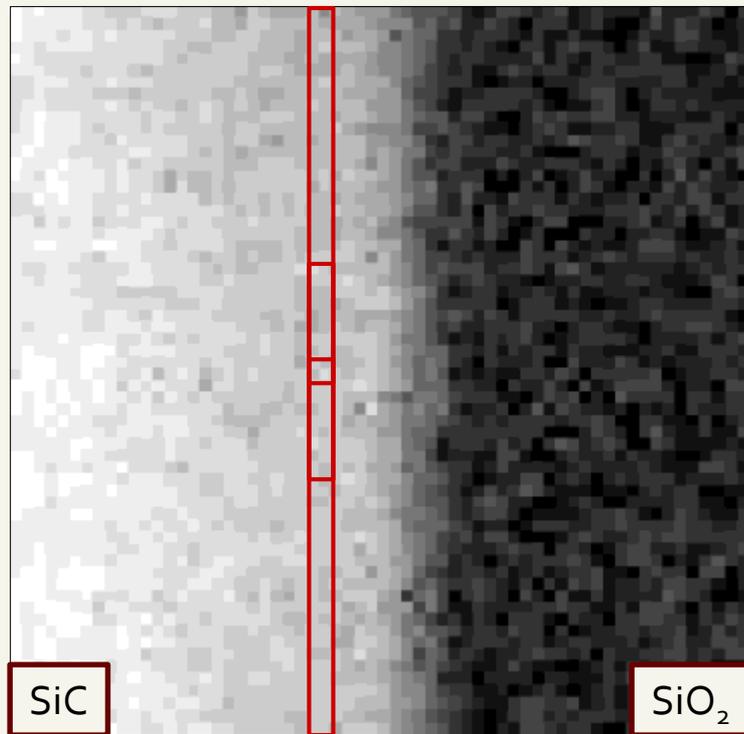


HAADF Image  
(60 minute anneal)

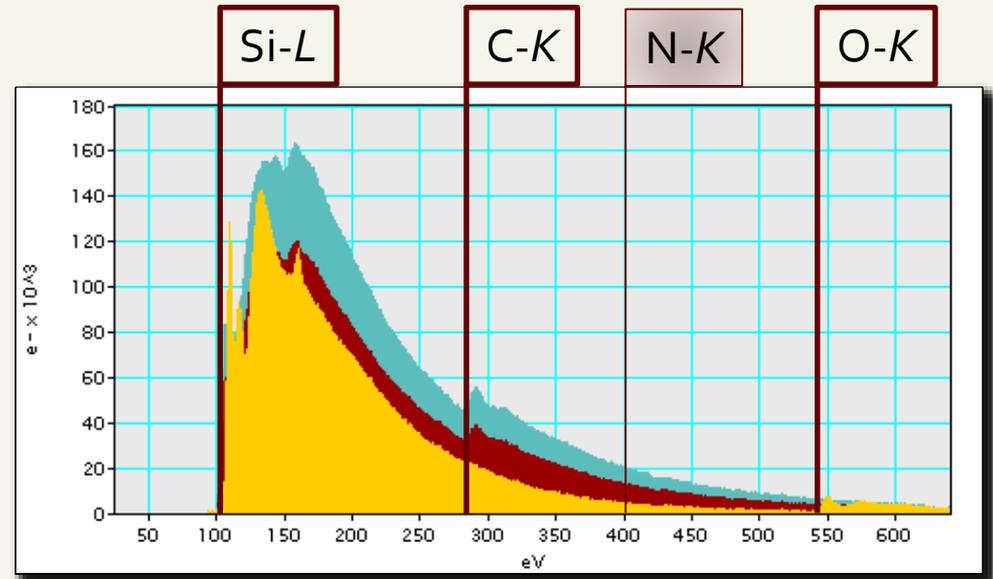


Spectrum Image  
(60 minute anneal)

# Spectrum Imaging



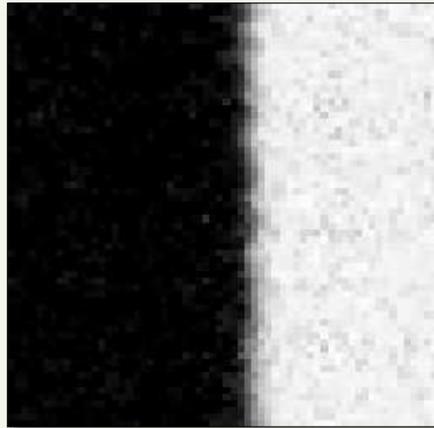
Spectrum Image  
(60 minute anneal)



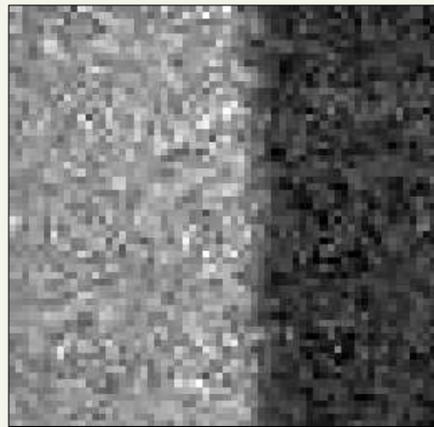
Background-subtracted spectrum  
(60 minute anneal)

# Elemental Composition Ratio

O

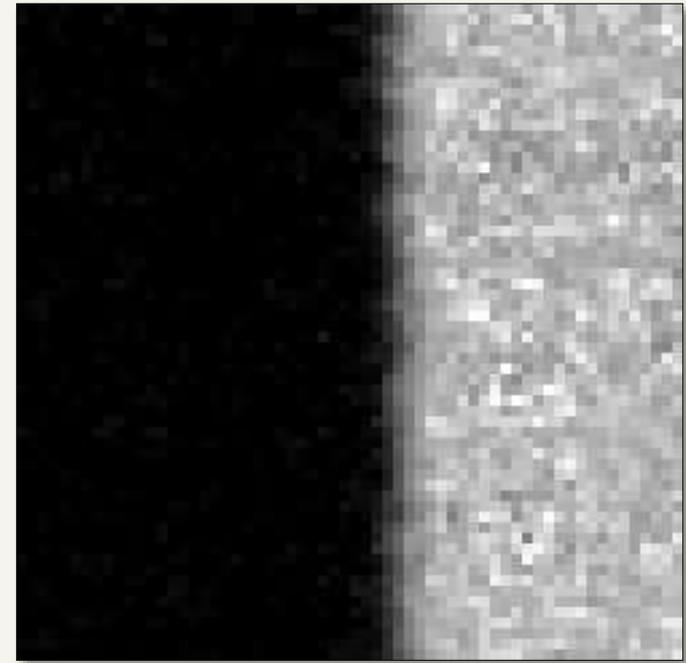


Si



Relative composition maps  
(60 minute anneal)

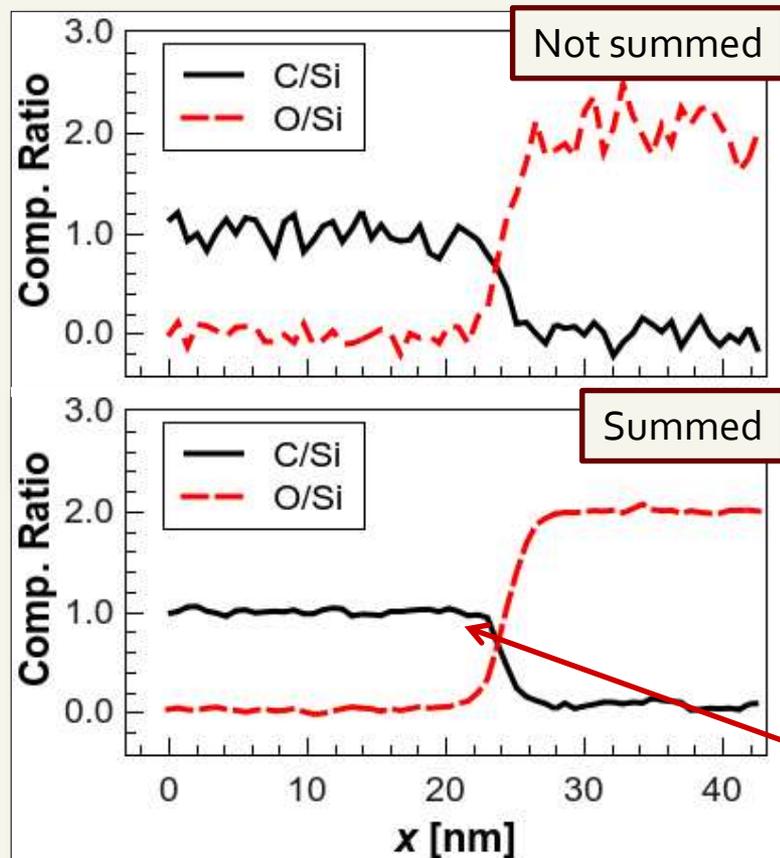
=



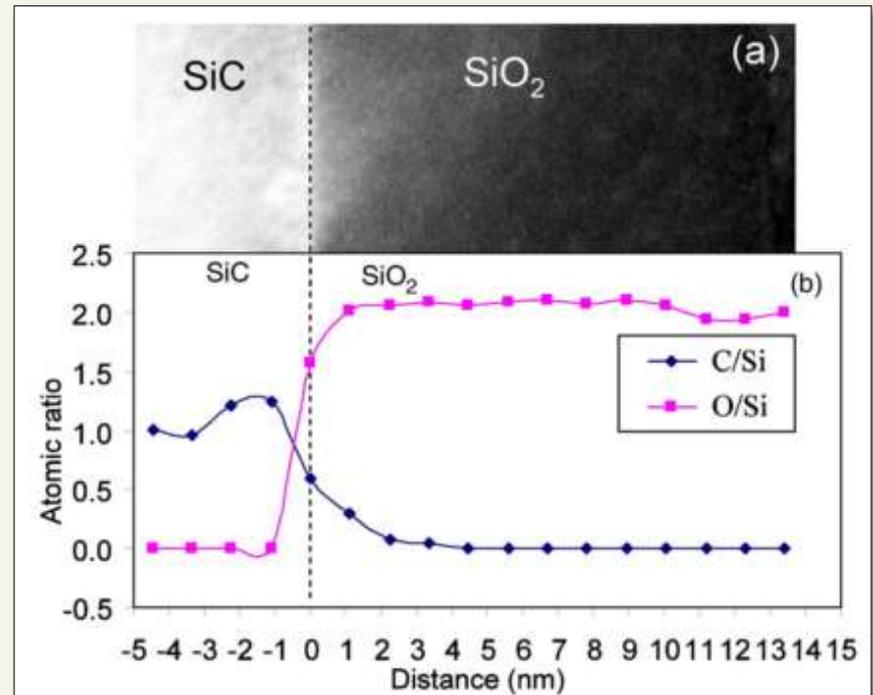
Composition Ratio Map  
(60 minute anneal)

# $w_{TL}$ from Composition Ratios

- Profile of atomic ratio maps:



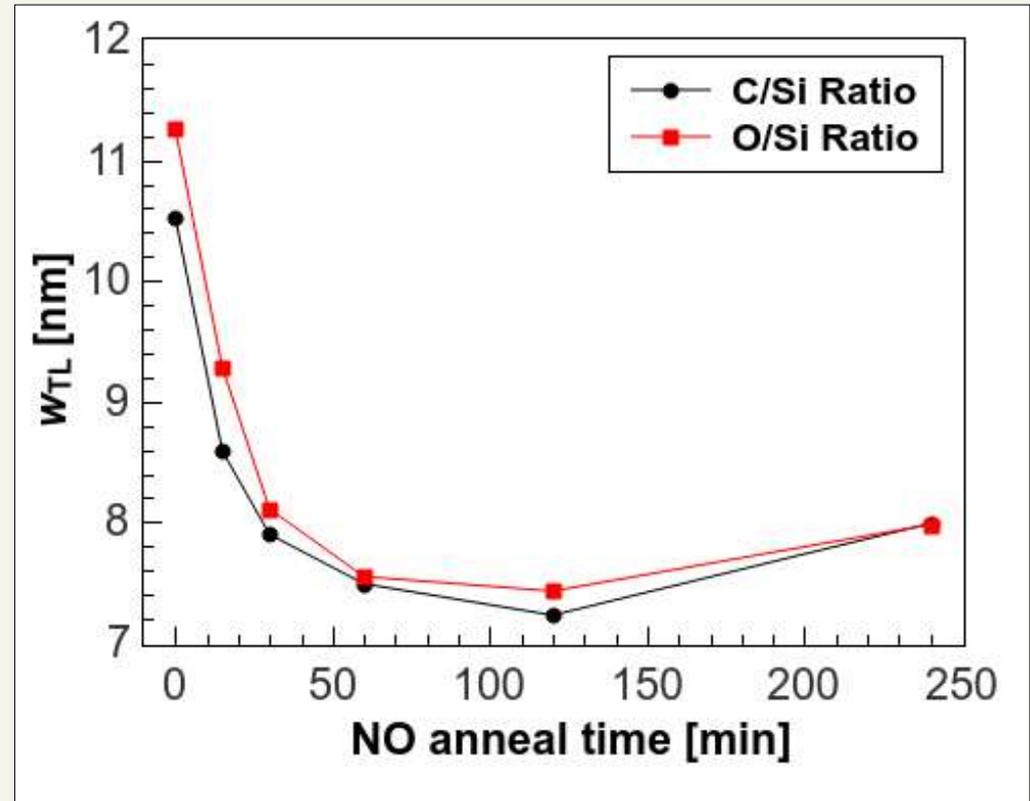
- Use  $\frac{d}{dx}$  of profile to find  $w_{TL}$ :



No excess C  
at interface

# Results (composition ratios)

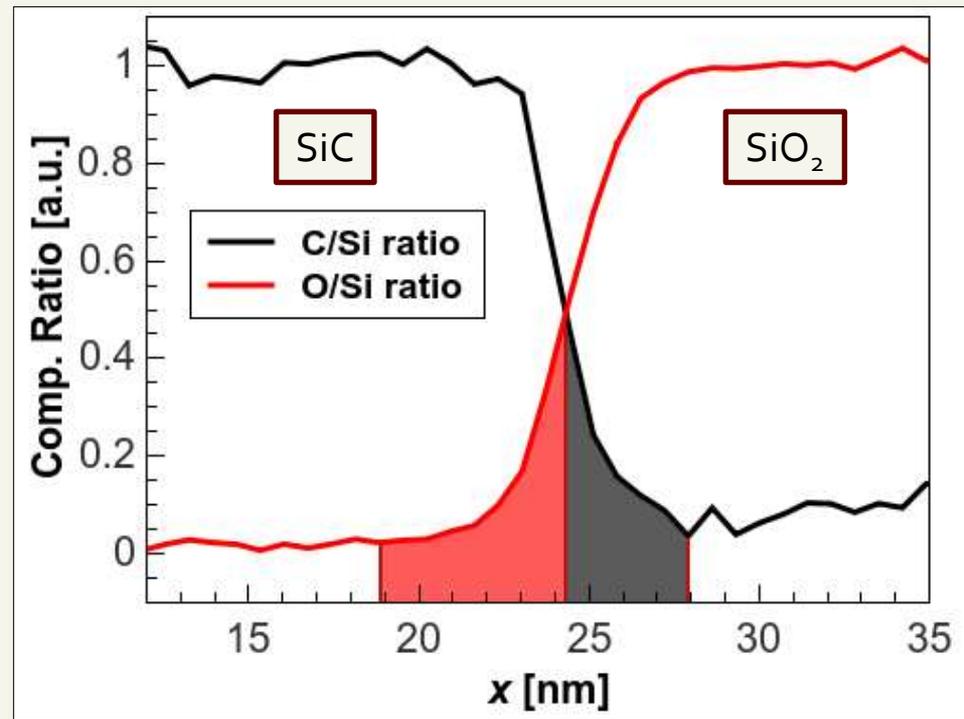
- $w_{TL}$  decreases as anneal time increases
  - EELS signal from 240 min anneal sample very noisy (C implantation)
- NO anneal results in significant improvement!
  - Removal of defects
  - Smoothing of interface<sup>1</sup>
- $\frac{O}{Si}$  slightly larger than  $\frac{C}{Si}$ 
  - Significant difference?



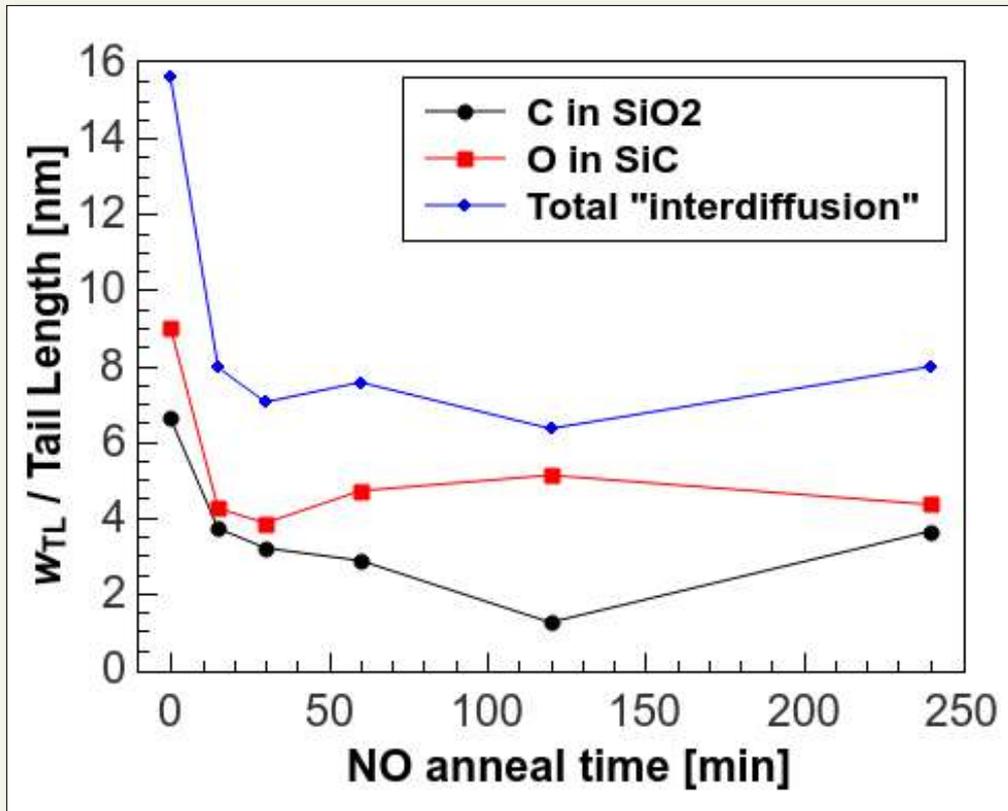
<sup>1</sup> P. Tanner, *et al.* Journal of Electronic Materials 28, 109–111 (1999).

# “Interdiffusion” lengths

- Useful to see tails of C concentration in  $\text{SiO}_2$  and O in SiC
  - Normalized bulk concentrations and measured tails with derivative



# Results ("Interdiffusion")



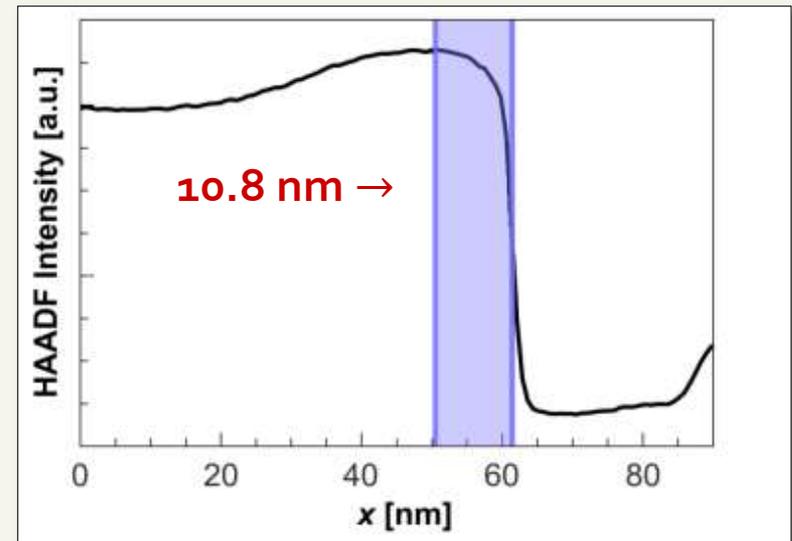
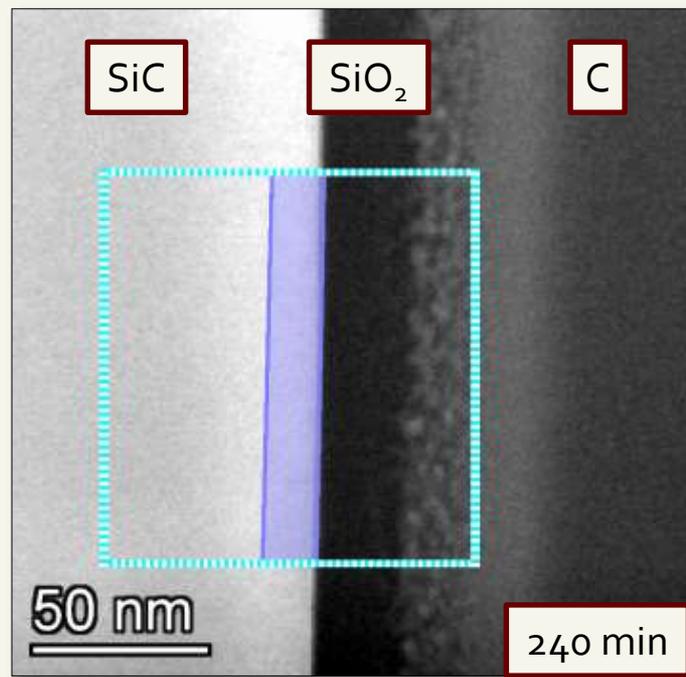
- Again, NO anneal shows significant improvement
- O tail in SiC always larger than C tail in SiO<sub>2</sub>
- Why?
  - C efficiently removed during oxidation<sup>1</sup>
  - O solubility in SiC very low<sup>2</sup>

<sup>1</sup> M. Di Ventra and S. Pantelides, Phys. Rev. Lett. **83**, 1624 (1999).

<sup>2</sup> M. Di Ventra and S. Pantelides, J. Electro. Mater. **29**, 353 (2000).

# HAADF-STEM Image Intensity<sup>1</sup>

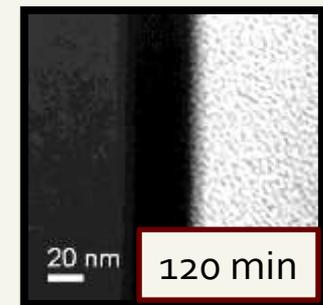
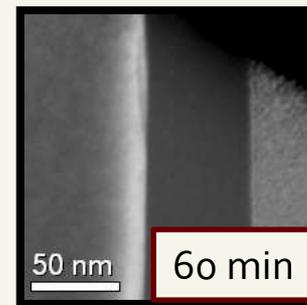
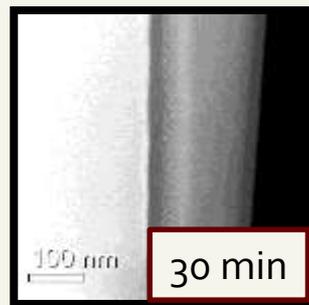
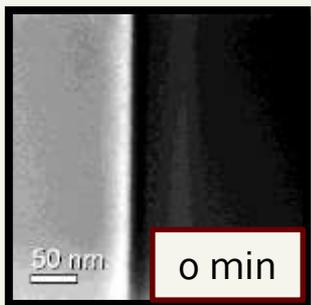
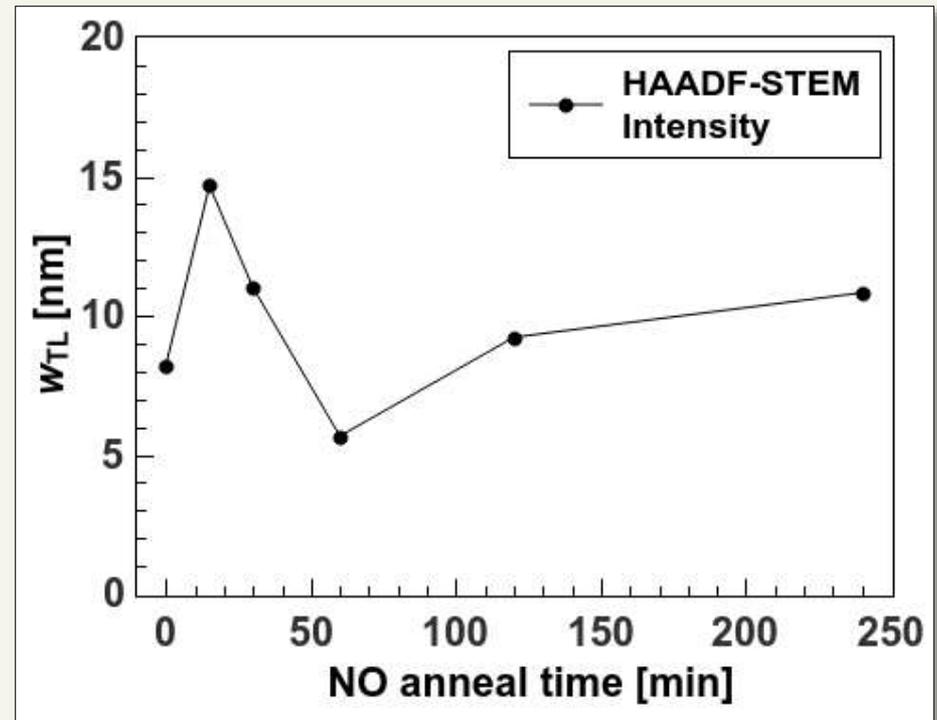
- Z-contrast from enhanced scattering cross-sections of heavier elements
  - $w_{TL}$  defined as width between peak and inflection point



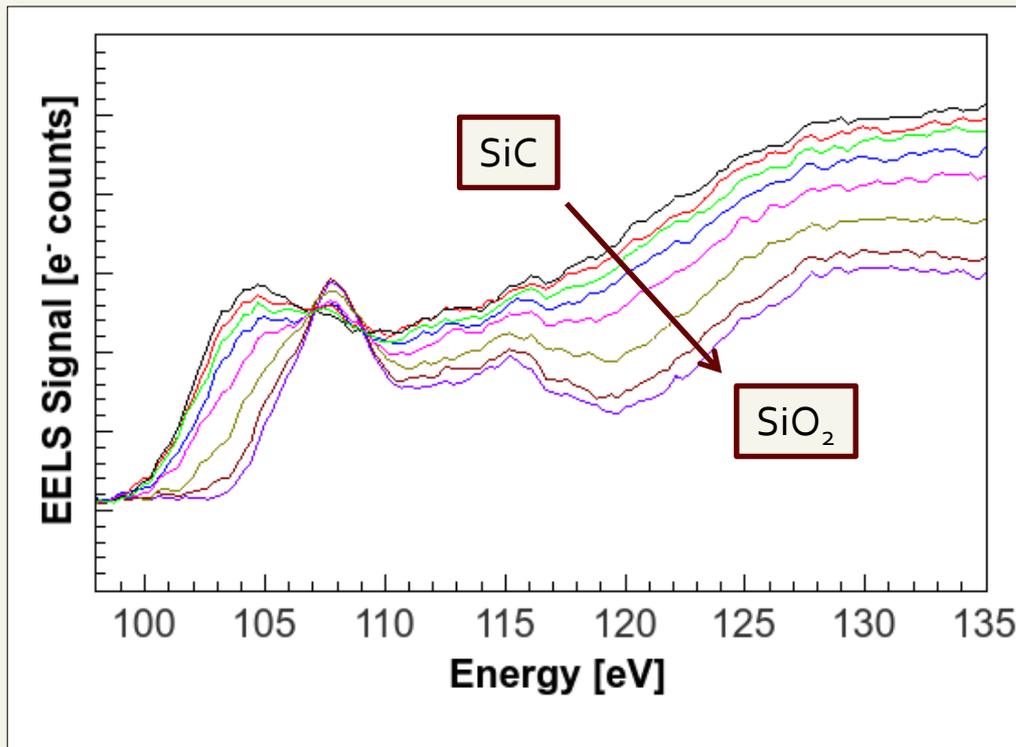
<sup>1</sup> After: T. Biggerstaff, *et al.* Appl. Phys. Lett. **95**, 032108 (2009).

# HAADF-STEM Results

- $w_{TL}$  results on same order as other methods
- Poorer overall trend in  $w_{TL}$ 
  - HAADF images varied substantially between samples
- No excess C, but bright intensity line
  - Thickness variations?



# Si- $L_{2,3}$ Chemical Shift

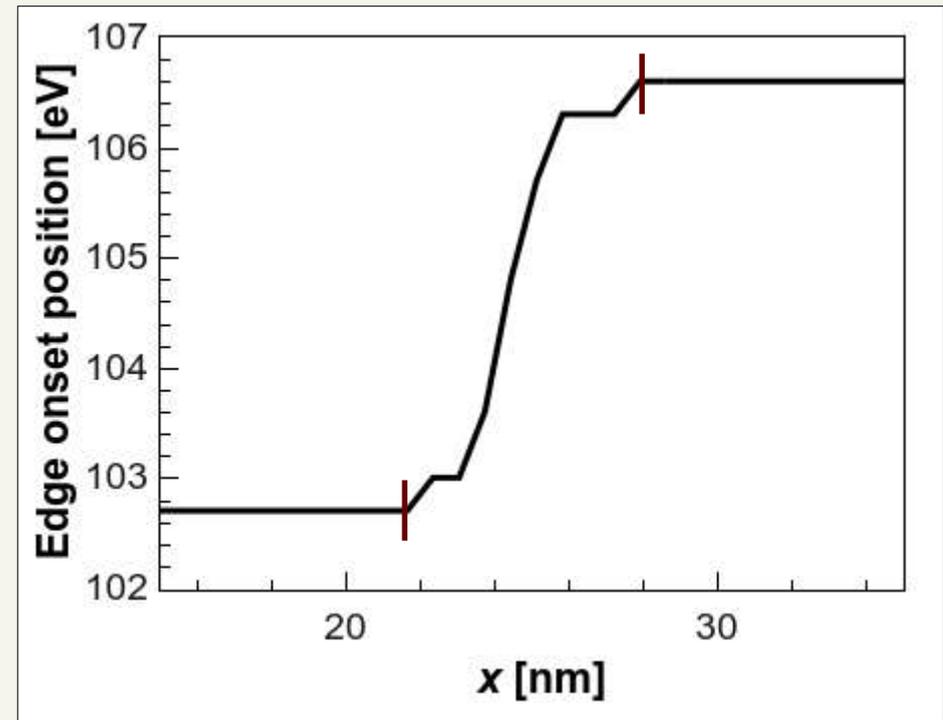


- EELS fine structure (ELNES) reflects local unoccupied density of states
  - Edge onset  $\rightarrow$  minimum energy needed to excite core shell  $e^-$
  - Semiconductor  $\rightarrow$  insulator
  - Band gap widens, core levels depressed relative to  $E_F$ <sup>1</sup>
    - Charge transfer from Si  $\rightarrow$  C/O
    - Onset shifts to higher energy

<sup>1</sup> D. Muller, Ultramicroscopy **78**, 163 (1999).

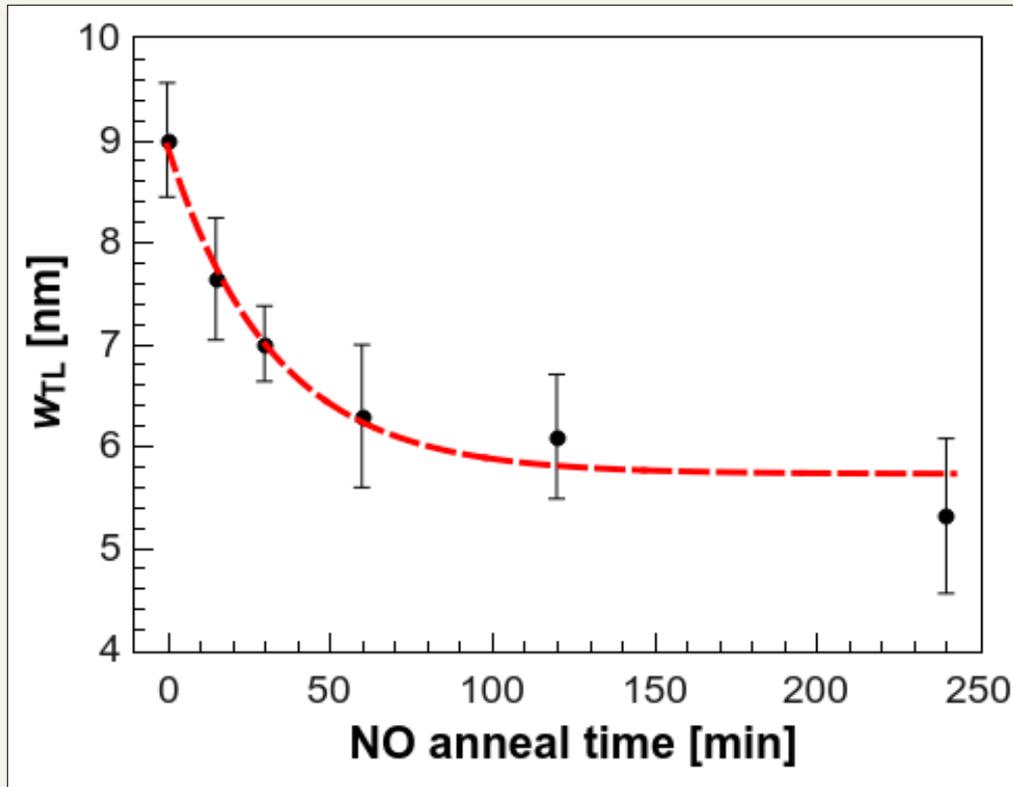
# Si- $L_{2,3}$ Chemical Shift

- Wrote script to find inflection point of edge onset<sup>1</sup>
  - Sum spectra parallel to interface
  - Take second derivative
  - Find zero and output position as function of distance
- Gradual and monotonic shift
  - Bonding changes
  - Possible strain
  - Implies a mix of Si-C and Si-O
  - Modeling needed



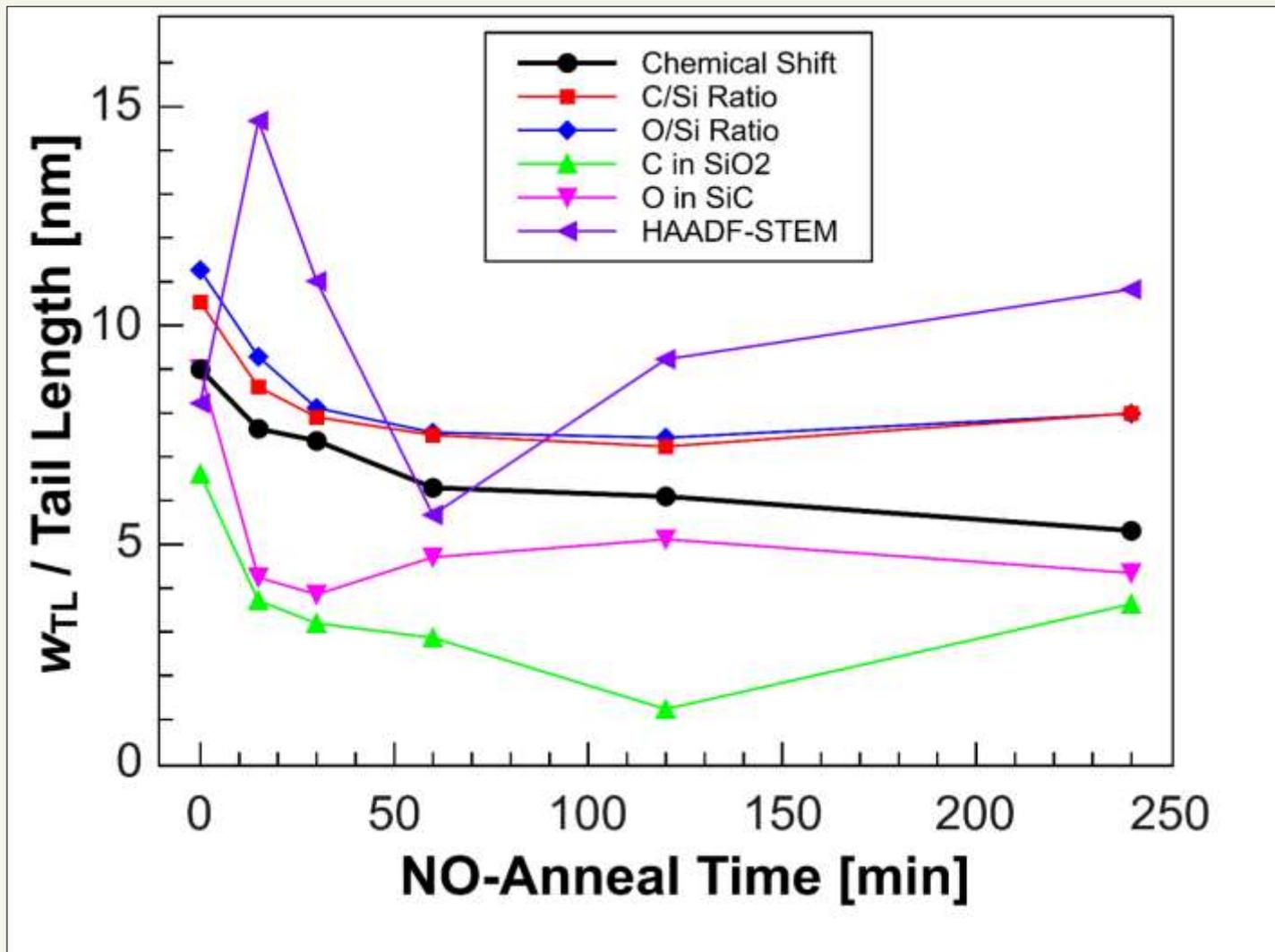
<sup>1</sup> D. Muller, P. Batson, and J. Silcox, Physical Review B **58**, 11970 (1998).

# Chemical Shift Results



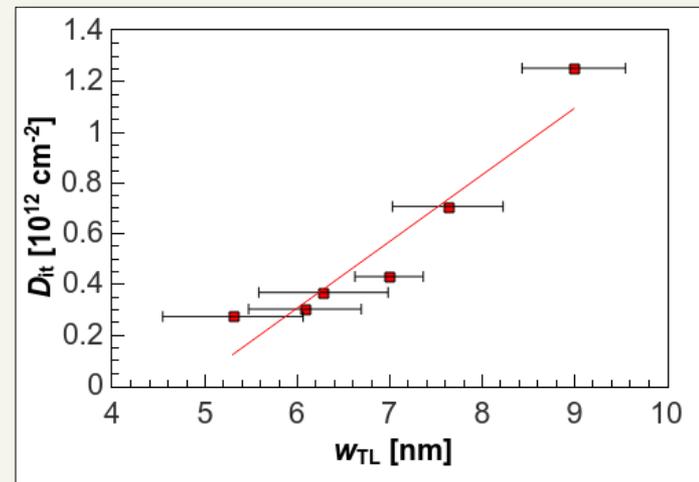
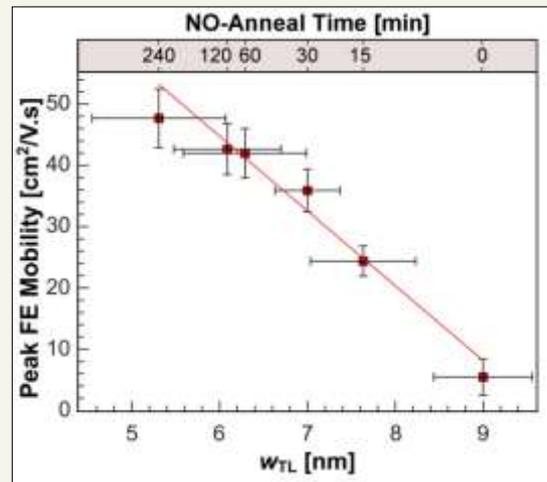
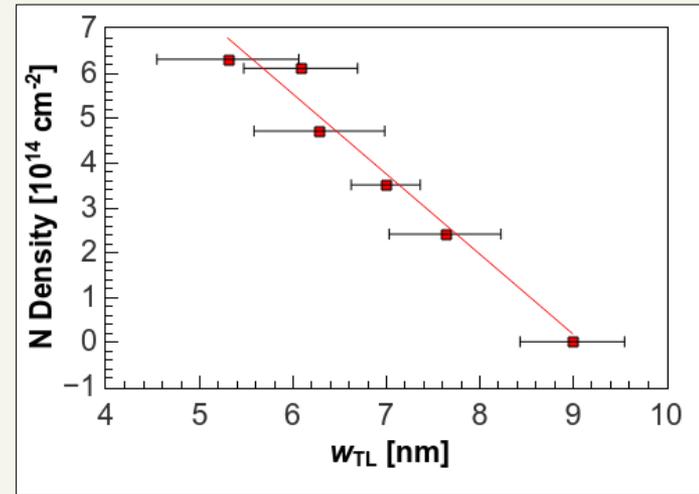
- Significant NO anneal improvement
  - Best method to track transition layer
  - (Relatively) insensitive to spectral noise
    - 240 min now fits trend
  - Clear exponential decay
- Characterizes different phenomenon
  - Bonding vs. composition

# All Results



# Electronic Measurements

- Data taken by J. Rozen
  - J. Rozen, *et al.* IEEE Trans. Electron. Dev. **58**, 3808 (2011).
  - J. Rozen, *et al.* J. Appl. Phys. **105**, 124506 (2009).
- $w_{TL}$  correlates:
  - Linearly with N density
  - Inverse-linearly with  $D_{it}$  and  $\mu_{FE}$
- Effect of NO?
  - Active removal of C (and O) at interface
  - Removes defects associated with these species



# Conclusions

- $w_{\text{TL}}$  decreases nonlinearly with increasing NO anneal time
  - All  $w_{\text{TL}}$  determination methods agree!
  - Chemical shift of Si- $L_{2,3}$  edge onset was most reliable
  - Inverse linear correlation of  $w_{\text{TL}}$  with  $\mu$  and N-density
  - Linear correlation of  $w_{\text{TL}}$  with  $D_{\text{it}}$
- No excess C on either side of interface
- No layer of N detected at interface – but should be able to see it
- Monotonic chemical shift of Si- $L_{2,3}$  edge
  - Indicates gradual progression of Si bonding character
- HAADF-STEM images are least reliable in  $w_{\text{TL}}$  determinations
  - EELS is more consistent; more informative (chemistry and bonding)
- Smallest transition region for 4hr anneal  $\rightarrow w_{\text{TL}} = 5.3$  nm
- Described objective  $w_{\text{TL}}$  determination method for future comparison

# Remaining Questions

- Structure and composition of interface, but what about bonding configurations?
  - High energy resolution ELNES study would give more bonding information
  - Could be correlated with XPS depth profiles across the interface
- How does NO treatment compare with N<sub>2</sub> and P passivation?
  - Do we observe the same  $w_{\text{TL}} - \mu$  correlation and how do  $w_{\text{TL}}$  values compare?
- Can we detect N concentrations at the interface using EELS?
  - Longer collection times, thicker sample, and optimized collection parameters needed

# Acknowledgements

- ARL Contracts W911NF-11-2-0044 and W911NF-07-2-0046.
- NispLab at UMD – supported by NSF and MRSEC
- Dr. Joshua Schumacher and Mike Hernandez at NIST

# THANK YOU

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Questions and comments?